Product Change Notification: CAAN-23VSTB654

Date:

16-Sep-2026

Product Category:

Memory

Notification Subject:

CCB 8103 Final Notice: Qualification of MMT as an additional assembly site for SST25PF040CT-40E/NP, SST25PF040CT-40E/NP-125, SST25PF040CT-40I/NP, SST25PF040CT-40V/NP, SST25WF020AT-40I/NP, USBF4100T-I/NP and USBF4100T-V/NP catalog part numbers (CPN) available in 8L UDFN (2x3x0.55mm) package.

Affected CPNs:

CAAN-23VSTB654_Affected_CPN_09162026.pdf
CAAN-23VSTB654_Affected_CPN_09162026.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of MMT as an additional assembly site for SST25PF040CT-40E/NP, SST25PF040CT-40E/NP-125, SST25PF040CT-40I/NP, SST25PF040CT-40V/NP, SST25WF020AT-40I/NP, USBF4100T-I/NP and USBF4100T-V/NP catalog part numbers (CPN) available in 8L UDFN (2x3x0.55mm) package.

Pre and Post Summary Changes:

	Pre Change	**Post Change**		**Change** (Yes/No)
Assembly Site	UTAC Thai Limited	UTAC Thai Limited	Microchip Technology Thailand	Yes

	(UTL-1) LTD. (NSEB)	(UTL-1) LTD. (NSEB)	(Branch) (MMT)	
Wire Material	Au	Au	Au	No
Die Attach Material	HR-5104 (PFAS-Free)	HR-5104 (PFAS-Free)	ATB F125E1 (PFAS-Free)	Yes
Molding Compound Material	G700LTD	G700LTD	G700LTD	No
Lead-Frame Material	EFTEC-64T	EFTEC-64T	EFTEC-64T	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability and on time delivery performance by qualifying MMT as an additional assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 17 July 2026 (date code: 2629)

Note Below EFSD: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	February 2026				**>**	**July 2026**					**>**	**September 2026**				
Work Week	06	07	08	09		27	28	29	30	31		36	37	38	39	40
Initial PCN Issue Date				X												
Qual Report Availability														X		
Final PCN Issue Date								X								
Estimated Implementation Date								X								

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: February 27, 2026: Issued initial notification.
July 15, 2026: Issued final notification. Provided estimated first ship date to be on July 17, 2026.
September 16, 2026: Re-issued final notification to attached the Qualification Report.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_CAAN-23VSTB654_Qual_Report.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

CAAN-23VSTB654 - CCB 8103 Final Notice: Qualification of MMT as an additional assembly site for SST25PF040CT-40E/NP, SST25PF040CT-40E/NP-125, SST25PF040CT-40I/NP, SST25PF040CT-40V/NP, SST25WF020AT-40I/NP, USBF4100T-I/NP and USBF4100T-V/NP catalog part numbers (CPN) available in 8L UDFN (2x3x0.55mm) package.

Affected Catalog Part Numbers (CPN):

SST25WF020AT-40I/NP

SST25PF040CT-40I/NP

SST25PF040CT-40E/NP

USBF4100T-V/NP

SST25PF040CT-40V/NP

SST25PF040CT-40E/NP-125

USBF4100T-I/NP



Qualification Report Summary

RELIABILITY LABORATORY

PCN #: CAAN-23VSTB654

Date:

September 8, 2026

Qualification of MMT as an additional assembly site for SST25PF040CT-40E/NP, SST25PF040CT-40E/NP-125, SST25PF040CT-40I/NP, SST25PF040CT-40V/NP, SST25WF020AT-40I/NP, USBF4100T-I/NP and USBF4100T-V/NP catalog part numbers (CPN) available in 8L UDFN (2x3x0.55mm) package.

PACKAGE QUALIFICATION REPORT

Purpose:

Qualification of MMT as an additional assembly site for SST25PF040CT-40E/NP, SST25PF040CT-40E/NP-125, SST25PF040CT-40I/NP, SST25PF040CT-40V/NP, SST25WF020AT-40I/NP, USBF4100T-I/NP and USBF4100T-V/NP catalog part numbers (CPN) available in 8L UDFN (2x3x0.55mm) package.

QUAL ID:	R2600486
QUAL ID Rev.:	B
MP CODE:	T0C01QPRXVA2
Part No.:	USBF4100T-V/NPVAO
Bonding No.:	BD-004200-02
CCB No.:	8103

Lead Frame

Paddle Size:	Chip on Lead design
Material:	EFTEC-64T
DAP Surface Prep:	Ag on lead only
Treatment:	Roughened
Process:	Etched
Lead Lock:	No
Part Number:	10100875
Lead Plating:	Matte tin

Bond Wire

Wire:	Au wire

Die Attach Material

Epoxy:	ATB F125E1
Conductive:	No

Mold Compound

Mold Compound:	G700LTD

Package

Type:	8L UDFN
Package Size:	2x3

Manufacturing Information

Assembly Lot No.
MMT-270101029.000
MMT-270201309.000
MMT-270201310.000

Result: **Pass**

Conclusion:
Qualification of T0C01 mask / USBF4100T-V/NPVAO product / Au wire in 8L UDFN 2x3 package at MMT site is qualified for MSL1 at 260ºC as per JEDEC J-STD-020 standard and is passed in accordance to Specified JEDEC and Mil Standards

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result
Moisture Soak Precondition Prior to Stresses	**MSL1:** 150°C 24 hours Bake, 168 hours Moisture Soak at 85°C/85%RH, 3x Reflow at 260°C **Electrical Test Tester:** NEXTEST_PV2 25°C, 85°C and 125°C	JESD22-A113 , JEDEC J-STD-020	231 units each lot / 3 lots	0/231, 0/231, 0/231	Pass
High Temp Storage	175°C / 504 hours **Electrical Test Tester:** NEXTEST_PV2 25°C, 85°C and 125°C	JESD22-A103	45 units / 1 lot	0/45	Pass
Temperature Cycling	-55°C / +150°C Air to Air / 1000 Cycles **Electrical Test Tester:** NEXTEST_PV2 85°C and 125°C	JESD22-A104	77 units each lot / 3 lots	0/77, 0/77, 0/77	Pass
	Wire Bond Pull		5 (0)	0/5	Pass
Biased HAST	+130°C / 85%RH / 96 hours / Bias Voltage: 3.6V **Electrical Test Tester:** NEXTEST_PV2 25°C, 85°C and 125°C	JESD22-A110	77 units each lot / 3 lots	0/77, 0/77, 0/77	Pass
Unbiased HAST	+130°C / 85%RH / 96 hours **Electrical Test Tester:** NEXTEST_PV2 25°C	JESD22-A118	77 units each lot / 3 lots	0/77, 0/77, 0/77	Pass
Solderability (0 Hr) Method 1: Dip and Look	Pb-free 8 hours Steam age. Dip at 245°C, 100% leads >95% lead coverage	J-STD-002 / JESD22B-102	22 units / 1 lot	0/22	Pass
Wire Pull	Bond Strength Data Assembly	Mil. Std. 883-2011	5 units / 1 lot	0/5	Pass
Bond Shear	Bond Strength Data Assembly	CDF-AEC-Q1 00-001	5 units / 1 lot	0/5	Pass